

NEI	Work Instruction		Page 1 of 5
Title: Unit Disassembly for WEEE			
Document Number / Disk File: 597-786-1410-00	By: Jegan Easwaram	Current Rev: 0A	Date: 04/21/2011
Assemblies Covered: S-1410 (786-1410-0X, 786-1410-0X, 786-1410-0X, 786-1410-0X)			



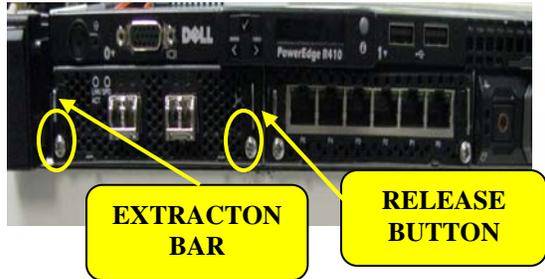
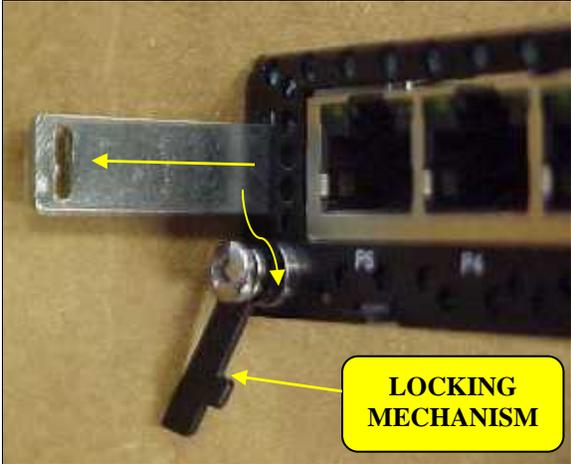
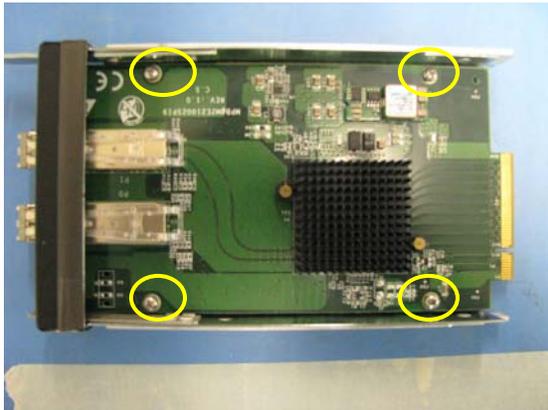
Revision	Date	ECO #	Revised By	Description of Changes
0A	04/21/11	P1143	Jegan Easwaram	Initial Release

Tools Required:

- #2 Phillips Screwdriver
- #1 Phillip Screwdriver
- Wrist grounding strap

NEI	Work Instruction		Page 2 of 5
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NOTE: Disconnect any AC Power Cords attached to the power supplies before disassembly of the unit.

1.	<p>Removal of the front I/O card(s) requires a #1 Philips screwdriver.</p> <ol style="list-style-type: none"> a. Loosen the two screws. b. Slide the locking mechanisms on the front of the I/O card. c. Pull the extraction bar on the left. d. Press the release button towards left. e. Extract the I/O card by pulling the extraction bar. f. Follow the same steps for the second card (if present) 	 
2.	<p>Removal of the PCB requires a #1 Philips screwdriver.</p> <ol style="list-style-type: none"> a. Remove the four (4) screws securing PCB to the case. b. Remove the PCB out of the case. c. Discard Sheet Metal Case, Screw, and PCB in the appropriate Recycling Bin. 	

NEI	Work Instruction		Page 3 of 5
Title: Unit Disassembly for WEEE			
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Removal instructions for the rest of the components can be found by browsing to the following link:

<http://support.dell.com/support/edocs/systems/peR410/en/HOM/HTML/install.htm#wp1181255>

Removal instructions for the rest of the components also embedded in this document.



Manual_WEEE.pdf

Note: Only follow the removal portion of the instructions in this document.

NEI	Work Instruction		Page 4 of 5
Title: Unit Disassembly for WEEE			
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PRODUCT FAMILY
Power Edge Server Family

PURPOSE

The intent of this document is to provide guidance to recyclers on the presence of materials and components at the product / family level, as required by the EU WEEE Directive 2002/96/EC. This document should also help direct recyclers to proper methods for removing parts and general product disassembly instructions.

PRODUCT DISASSEMBLY INSTRUCTIONS

Most parts can be removed easily by hand. In some cases common household tools such as Philips and/or flat-head screw drivers may be necessary. To remove discrete components such as the electrolytic capacitors, needle-nose pliers may be helpful. Instructions for removing parts in each product can be found in the User Documentation originally provided with the product. This documentation can be found online: <http://support.dell.com/support/systemsinfo/documentation.aspx?c=us&cs=19&l=en&s=dhs&-cat=12&-subcat=89>.

PRODUCT MATERIAL INFORMATION

The following substances, preparations, or components should be disposed of or recovered separately from other WEEE in compliance with Article 4 of EU Council Directive 75/442/EEC.

Batteries	Mercury	Dell does not use internal batteries based on Mercury (Hg) and its compounds.
	Cadmium	Dell does not use internal batteries based on Cadmium (Cd) and its compounds.
	Lead	Dell does not use internal batteries based on Lead (Pb) and its compounds.
	Other	Dell servers use Lithium Primary Coin Cells. Depending on the feature set, some may also include Lithium Ion secondaries. Additional features such as add in PERC, RAID, or DRAC cards may include a Lithium Ion Button Cell or Nickel Metal Hydride batteries.
Mercury	Lamps, Bulbs, and other Lighting Applications	Product does not contain a Mercury based lamp or bulb.
	Other Uses	Other parts used in Dell products can not contain intentionally added Mercury.
Liquid Crystal Displays (LCD) - > 100 cm ²		Product does not contain an LCD greater than 100 cm ² .
Cathode Ray Tubes (CRT)		Product does not contain a CRT.

NEI	Work Instruction		Page 5 of 5
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Plastic containing Brominated flame retardants other than in PCB / PCA	<p>This product may contain plastic parts greater than 25 grams. Many of these parts are bromine free. Regardless, these parts are labeled (usually molded directly into the plastic) per ISO 11469:2000(E).</p> <p>A typical label would look like: > Polymer Abbreviation - FR(#) < i.e. > PC + ABS FR(40) <</p> <p>Flame retardant codes (FR(#)) are given in ISO 1043-4. Codes for some Brominated flame retardants: 14 aliphatic/alicyclic Brominated compounds 15 aliphatic/alicyclic Brominated compounds in combination with antimony compounds 16 aromatic Brominated compounds (excluding Brominated diphenyl ether and biphenyls) 17 aromatic Brominated compounds (excluding Brominated diphenyl ether and biphenyls) in combination with antimony compounds 22 aliphatic/alicyclic chlorinated and Brominated compounds 42 Brominated organic phosphorus compounds</p>
Capacitors with PCB's	Dell does not use capacitors with PCB.
Electrolyte capacitors (height > 25mm, diameter > 25mm)	Electrolytic capacitors (height and/or diameter greater than 25mm) are not used on Dell motherboards. However, these capacitors are often present in power supply units (silver box).
Asbestos and its compounds	Parts used in Dell products cannot contain asbestos or its compounds.
Refractory ceramic fibres	Parts used in Dell products cannot contain refractory ceramic fibers.
Radio-active substances	Parts used in Dell products cannot contain Radio-active substances.
Beryllium and its compounds (including Beryllium Oxide)	Beryllium may be present in electronic components as a copper beryllium alloy, which contains less than 2% beryllium. CuBe alloys may be used in various components such as connectors, switches, relays, current carrying springs, integrated circuit sockets, and RF shielding.
Gasses - which fall under Regulation (EC) 2037/2000 and all hydrocarbons (HC)	Parts used in Dell products do not contain gasses which fall under Regulation (EC 2037/2000) and all hydrocarbons (HC).
Components with pressurized gas which need special attention (Pressure > 1,5bar)	Product does not contain parts with pressurized gas.
Liquids	This product may contain a heatsink heat pipe. Heat pipes contain a very small amount of very pure water.

DELL CORPORATE ENVIRONMENTAL INFORMATION

Information on Dell's Environmental initiatives, policies, programs and goals can be found at www.dell.com/environment.